


CMOS Sensor

Purpose	Inspection Solutions for CMOS Sensors to meet stringent assembly and final visual out going quality requirement.
Technology	<ol style="list-style-type: none"> 1. Sub Micron AOI – Defect Size from 0.5um. Microscope objective, multiple direction illumination design combined field proven sub micron defect detection algorithm to detect sensor defects such as contamination, structure damage, fab defects. 2. Macro AOI – Defect Size from 5um. Packaged CMOS Sensors in JEDEC Tray. Inspection coverage includes all sides- Top, Bottom and Side walls defects. Offers capability to detect defects on glass defects, contamination, chipping and ceramic cracks 3. Side Wall Inspection – Inspect side wall defects include delamination, ceramic crack and void 4. Void/Bubble Inspection – Using Optical Interference technique to Detect surface topology variation caused by voids/bubbles between photodiode and top surface layers of CMOS image sensor 5. Auto Defect Classification (ADC) – Applying Rule and Region based automatic defect classification of defect signatures to identify, isolate and improve process issues.

STI Products	Sub Micron AOI	Macro AOI	Side Wall Inspection	Void/Bubble Inspection	ADC
 iFocus – Wafer 2D & 3D Scan					
 Hexa – Tray 2D & 3D Scan					